

WHAT IS CLAIMED IS:

1. An apparatus comprising:
 - an integrated circuit package comprising a package power contact and a package ground contact;
 - 5 an interposer to physically receive a portion of the package and comprising a lip; and a first card comprising a card power contact to interface with the package power contact and a card ground contact to interface with the package ground contact, the first card defining an opening to receive a portion of the interposer, wherein the lip is to support a portion of the first card.
- 10 2. An apparatus according to Claim 1,
 - the integrated circuit package comprising a package input/output (I/O) contact; and the interposer comprising an interposer I/O contact to interface with the package I/O contact.
- 15 3. An apparatus according to Claim 1, the portion of the interposer to be received by the opening so as to substantially prevent motion of the first card with respect to the interposer in the plane of the opening.
- 20 4. An apparatus according to Claim 1, the interposer further comprising a second interposer I/O contact electrically coupled to the interposer I/O contact, and further comprising:
 - a second card comprising a card I/O contact to interface with the second interposer I/O contact.

5. An apparatus according to Claim 1, further comprising:
one or more voltage regulator elements mounted on the first card.

- 10 6. An apparatus according to Claim 5,
the first card comprising a power interface to receive power directly from a power supply.

- 15 7. An apparatus according to Claim 5, further comprising:
an integrated circuit die electrically coupled to the package power contact and the package ground contact; and
a heatsink thermally coupled to the integrated circuit die and to one or more of the one or more voltage regulator elements.

- 20 8. An apparatus comprising:
one or more voltage regulator elements;
an integrated circuit die; and
a heatsink thermally coupled to the integrated circuit die and to one or more of the one or more voltage regulator elements.

- 25 9. An apparatus according to Claim 8, further comprising:
an integrated circuit package to support the integrated circuit die;
an interposer to physically receive a portion of the package and comprising a lip; and
a first card on which the one or more of the one or more voltage regulator elements are mounted, the first card defining an opening to receive a portion of the interposer,

wherein the lip is to support a portion of the first card.

10. An apparatus comprising:

an interposer comprising a lip, the interposer to support a portion of an integrated

5 circuit package; and

a card defining an opening, the opening to receive a portion of the interposer, the card to couple to the integrated circuit package, and the lip to support a portion of the card.

11. An apparatus according to Claim 10,

10 wherein the card comprises a card power contact and a card ground contact to

respectively interface with a package power contact and a package ground contact of the integrated circuit package.

12. An apparatus according to Claim 10,

15 the interposer further comprising an interposer I/O contact to interface with a

package input/output (I/O) contact of the integrated circuit package.

13. An apparatus according to Claim 12, the interposer further comprising a second

interposer I/O contact electrically coupled to the interposer I/O contact, and further

20 comprising:

a second card comprising a card I/O contact to interface with the second interposer

I/O contact.

14. An apparatus according to Claim 10, the portion of the interposer to be received

25 by the opening so as to substantially prevent motion of the card with respect to the

interposer in the plane of the opening.

15. An apparatus according to Claim 10, further comprising:
one or more voltage regulator elements mounted on the card.

5 16. An apparatus according to Claim 15,
the card comprising a power interface to receive power directly from a power supply.

10 17. A system comprising:
one or more voltage regulator elements;
an integrated circuit die;
a heatsink thermally coupled to the integrated circuit die and to one or more of the
one or more voltage regulator elements; and
a double data rate memory electrically coupled to the integrated circuit die.

15 18. A system according to Claim 17, further comprising:
an integrated circuit package to support the integrated circuit die;
an interposer to physically receive a portion of the package and comprising a lip; and
a first card on which the one or more of the one or more voltage regulator elements
are mounted, the first card defining an opening to receive a portion of the interposer,
20 wherein the lip is to support a portion of the first card.

19. A system according to Claim 17, further comprising:
a motherboard electrically coupled to the integrated circuit die and to the memory.